

DECLARATION FOR PATENT APPLICATION

Docket Number (Optional)

MR2349-794

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled POWER-EQUALIZING MULTI-CHANNEL FIBER LASER ARRAY, the specification of which is attached hereto unless the following box is checked:

☐ was filed on _____ as United States Application Number or PCT International Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR §1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Priority Not Claimed

(Number) (Country) (Day/Month/Year Filed)

☐

(Number) (Country) (Day/Month/Year Filed)

☐

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

(Application Number) (Filing Date)

(Application Number) (Filing Date)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Number) (Filing Date) (Status-patented, pending, abandoned)

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I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: **Morton J. Rosenberg, Reg. #26,049; David I. Klein, Reg. #33,253; Jun Y. Lee, Reg. #40,262**

Address all telephone calls to **410-465-6678**

Address all correspondence to **Rosenberg, Klein & Lee
3458 Ellicott Center Drive-Suite 101
Ellicott City, MD 21043**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name) HSIEN-KUEI LIAO (FAMILY NAME: LIAO)

Inventor's signature Hsien-Kuei Liao Date Dec 24, 2001

Citizenship TAIWAN, R.O.C.

Mailing Address 7F-1, NO. 23, LANE 18, JUI PING RD., YANG MEI JEN, TAOYUAN HSIEN, TAIWAN, R.O.C.

Full name of second joint inventor, if any (given name, family name) PIE-YAU CHIEN (FAMILY NAME: CHIEN)

Second Inventor's signature Pie-Yau Chien Date Dec 26, 2001

Citizenship TAIWAN, R.O.C.

Mailing Address 4F, NO. 4, LANE 85, CHUANG CHING RD., PANCHIAO CITY, TAIPEI HSIEN, TAIWAN, R.O.C.

☐ Additional Inventors are being named on separately numbered sheets attached hereto.

Third Joint Inventor	HONG-YIH TSENG (FAMILY NAME: TSENG)	
Inventor's Signature	<i>Hong-Yih Tseng</i>	Date <i>Jan. 14, 2002</i>
Citizenship	TAIWAN, R.O.C.	
Mailing Address	7F-1, NO.42, LANE 245, WU LING RD., HSINCHU CITY, TAIWAN, R.O.C.	

Fourth Joint Inventor	SIEN CHI (FAMILY NAME: CHI)	
Inventor's Signature	<i>Siен Chi</i>	Date <i>Jan. 14, 2002</i>
Citizenship	TAIWAN, R.O.C.	
Mailing Address	9F-1, NO.25, CHIEN CHUNG I RD., HSINCHU CITY, TAIWAN, R.O.C.	

Fifth Joint Inventor		
Inventor's Signature		Date
Citizenship		
Mailing Address		

Sixth Joint Inventor		
Inventor's Signature		Date
Citizenship		
Mailing Address		